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Object of Declaration: MCP9600 Thermocouple IC Evaluation Board

EU Declaration of Conformity

Manufacturer: Microchip Technology Inc.
2355 W. Chandler Blvd.
Chandler, Arizona, 85224-6199
USA

This declaration of conformity is issued by the manufacturer.

The development/evaluation tool is designed to be used for research and development in a laboratory environment. This development/evaluation tool is not a Finished Appliance, nor is it intended for incorporation into Finished Appliances that are made commercially available as single functional units to end users under EU EMC Directive 2004/108/EC and as supported by the European Commission’s Guide for the EMC Directive 2004/108/EC (8th February 2010).

This development/evaluation tool complies with EU RoHS2 Directive 2011/65/EU.

This development/evaluation tool, when incorporating wireless and radio-telecom functionality, is in compliance with the essential requirement and other relevant provisions of the R&TTE Directive 1999/5/EC and the FCC rules as stated in the declaration of conformity provided in the module datasheet and the module product page available at www.microchip.com.

For information regarding the exclusive, limited warranties applicable to Microchip products, please see Microchip’s standard terms and conditions of sale, which are printed on our sales documentation and available at www.microchip.com.

Signed for and on behalf of Microchip Technology Inc. at Chandler, Arizona, USA

Derek Carlson
VP Development Tools

Date
12-Sep-14
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INTRODUCTION

This chapter contains general information that will be useful to know before using the MCP9600 Thermocouple IC Evaluation Board. Items discussed in this chapter include:

- Document Layout
- Conventions Used in This Guide
- Recommended Reading
- The Microchip Web Site
- Customer Support
- Revision History

DOCUMENT LAYOUT

This document describes how to use the MCP9600 Thermocouple IC Evaluation Board as a development tool. The document is organized as follows:

- **Chapter 1. “Product Overview”** – This chapter includes important information about the MCP9600 Thermocouple IC Evaluation Board.
- **Chapter 2. “Installation and Operation”** – This chapter includes a detailed description of each function of the evaluation board and instructions on how to begin using the board.
- **Appendix A. “Schematic and Layouts”** – Shows the schematic and layout diagrams for MCP9600 Thermocouple IC Evaluation Board.
- **Appendix B. “Bill of Materials (BOM)”** – Lists the parts used to build the MCP9600 Thermocouple IC Evaluation Board.
## CONVENTIONS USED IN THIS GUIDE

This manual uses the following documentation conventions:

### DOCUMENTATION CONVENTIONS

<table>
<thead>
<tr>
<th>Description</th>
<th>Represents</th>
<th>Examples</th>
</tr>
</thead>
<tbody>
<tr>
<td>Arial font:</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Italic characters</td>
<td>Referenced books</td>
<td><em>MPLAB® IDE User’s Guide</em></td>
</tr>
<tr>
<td>Emphasized text</td>
<td></td>
<td><em>...is the only compiler...</em></td>
</tr>
<tr>
<td>Initial caps</td>
<td>A window</td>
<td>the Output window</td>
</tr>
<tr>
<td></td>
<td>A dialog</td>
<td>the Settings dialog</td>
</tr>
<tr>
<td></td>
<td>A menu selection</td>
<td>select Enable Programmer</td>
</tr>
<tr>
<td>Quotes</td>
<td>A field name in a window or dialog</td>
<td>“Save project before build”</td>
</tr>
<tr>
<td>Underlined, Italic text with right</td>
<td>A menu path</td>
<td><em>File&gt;Save</em></td>
</tr>
<tr>
<td>angle bracket</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Bold characters</td>
<td>A dialog button</td>
<td><em>Click OK</em></td>
</tr>
<tr>
<td></td>
<td>A tab</td>
<td><em>Click the Power tab</em></td>
</tr>
<tr>
<td>N'Rnnnn</td>
<td>A number in verilog format, where N is the total</td>
<td>4'b0010, 2'hF1</td>
</tr>
<tr>
<td></td>
<td>number of digits, R is the radix and n is a digit.</td>
<td></td>
</tr>
<tr>
<td>Text in angle brackets &lt; &gt;</td>
<td>A key on the keyboard</td>
<td>Press &lt;Enter&gt;, &lt;F1&gt;</td>
</tr>
<tr>
<td>Courier New font:</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plain Courier New</td>
<td>Sample source code</td>
<td><em>#define START</em></td>
</tr>
<tr>
<td>Filenames</td>
<td></td>
<td></td>
</tr>
<tr>
<td>File paths</td>
<td>c:\mcc18\h</td>
<td></td>
</tr>
<tr>
<td>Keywords</td>
<td>_asm, _endasm, static</td>
<td></td>
</tr>
<tr>
<td>Command-line options</td>
<td>-Opa+, -Opa-</td>
<td></td>
</tr>
<tr>
<td>Bit values</td>
<td>0, 1</td>
<td></td>
</tr>
<tr>
<td>Constants</td>
<td>0xFF, ‘A’</td>
<td></td>
</tr>
<tr>
<td>Italic Courier New</td>
<td>A variable argument</td>
<td><em>file.o, where file can be any valid filename</em></td>
</tr>
<tr>
<td>Square brackets [ ]</td>
<td>Optional arguments</td>
<td><em>mcc18 [options] file [options]</em></td>
</tr>
<tr>
<td>Curly brackets and pipe character:</td>
<td>Choice of mutually exclusive arguments; an OR</td>
<td>*errorlevel {0</td>
</tr>
<tr>
<td>Ellipses...</td>
<td>Replaces repeated text</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Represents code supplied by user</td>
<td></td>
</tr>
<tr>
<td></td>
<td>void main (void) {</td>
<td></td>
</tr>
<tr>
<td></td>
<td>... }</td>
<td></td>
</tr>
</tbody>
</table>
RECOMMENDED READING

This user's guide describes how to use MCP9600 Thermocouple IC Evaluation Board. Other useful documents are listed below. The following Microchip documents are available and recommended as supplemental reference resources:

- **MCP9600 Data Sheet** – “Thermocouple Voltage to Temperature Converter, ±1.5°C Maximum Accuracy” (DS20005426)
  
  This data sheet provides detailed information regarding the MCP9600 device.

- **PIC18F2455/2550/4455/4550 Data Sheet** – “28/40/44-Pin, High-Performance, Enhanced Flash, USB Microcontrollers with nanoWatt Technology” (DS39632)
  
  This data sheet provides detailed information regarding the PIC18F2455/2550/4455/4550 devices.

THE MICROCHIP WEB SITE

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- **General Technical Support** – Frequently Asked Questions (FAQs), technical support requests, online discussion groups, Microchip consultant program member listing

- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

Customers should contact their distributor, representative or field application engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: http://www.microchip.com/support.

REVISION HISTORY

**Revision A (September 2015)**

- Original release of this document.
Chapter 1. Product Overview

1.1 INTRODUCTION

This chapter provides an overview of the MCP9600 Thermocouple IC Evaluation Board and covers the following topics:

• What is the MCP9600 Device?
• What is the MCP9600 Thermocouple IC Evaluation Board?
• What the MCP9600 Thermocouple IC Evaluation Board Kit Contains

1.2 WHAT IS THE MCP9600 DEVICE?

The MCP9600 is a Thermocouple Electromotive Force (EMF) to temperature converter. This device converts thermocouple EMF to degree Celsius with integrated Cold-Junction compensation. MCP9600 corrects the thermocouple nonlinear error characteristics of eight thermocouple types and outputs ±1.5°C accurate temperature data for the selected thermocouple. The correction coefficients are derived from the National Institute of Standards and Technology (NIST) ITS-90 Thermocouple Database.

1.3 WHAT IS THE MCP9600 THERMOCOUPLE IC EVALUATION BOARD?

The MCP9600 Thermocouple IC Evaluation Board is used to evaluate MCP9600 Thermocouple EMF voltage to degree Celsius converter. Users can easily evaluate all device features using a Type K thermocouple. The device also supports Types J, T, N, E, B, S and R thermocouples. Each of these types can be evaluated by replacing the Type K thermocouple connector with the corresponding connectors.

In addition, the MCP9600 Thermocouple IC Evaluation Board connects to a PC via a USB interface. Temperature can be data-logged using the Microchip Thermal Management Software Graphical User Interface (GUI).

1.4 WHAT THE MCP9600 THERMOCOUPLE IC EVALUATION BOARD KIT CONTAINS

The MCP9600 Thermocouple IC Evaluation Board package includes:

• MCP9600 Thermocouple IC Evaluation Board (ADM00665)
• Type K Thermocouple
• Mini USB Cable
• Important Information Sheet
Chapter 2. Installation and Operation

2.1 INTRODUCTION

The MCP9600 Thermocouple IC Evaluation Board enables users to easily evaluate all user-programmable features such as thermocouple selection, temperature alert limit settings, temperature resolutions and Power mode.

Items discussed in this chapter include:
• Required Tool
• Getting Started
• Microchip Thermal Management Software GUI
• Configuring the MCP9600
• Data Acquisition

2.2 REQUIRED TOOL

The Personal Computer (PC) shown in Figure 2-1 needs to run on Windows® 98 SE or later. It provides a convenient interface for the user, communicates with the board and provides power through the USB connection.

FIGURE 2-1: MCP9600 Thermocouple IC Evaluation Board Setup.
2.3 GETTING STARTED

This section describes how to power up and interface with the MCP9600 Thermocouple IC Evaluation Board.

2.3.1 Hardware Setup

1. The MCP9600 Thermocouple IC Evaluation Board has a mini USB connector for a PC interface. Connect the USB cable from the evaluation board to a PC.

2.3.2 Hardware Operation

The MCP9600 Thermocouple IC Evaluation Board is fully powered from a PC USB 5V source. Once power is applied via USB and the USB is successfully enumerated, the PIC® microcontroller is ready to receive commands from the host PC to program the MCP9600 settings or transfer temperature data.
The block diagram (Figure 2-3) shows that the thermocouple connector is directly connected to the MCP9600. The four Alert outputs are connected to test points for external connections. Additionally, these outputs are also connected to the microcontroller I/O pins so that the Alert Output statuses can be detected in software.

2.4 MICROCHIP THERMAL MANAGEMENT SOFTWARE GUI

The Microchip Thermal Management Graphical User Interface allows users to evaluate the MCP9600 for temperature-sensing applications. This software tool can be downloaded and installed from the evaluation board product page. The software requires the 'Microsoft.NET Framework' package. If this framework package is not installed on the computer, then the software will automatically download and install it. After the installation is successfully completed, the hardware is required to start the graphical user interface.

Once the hardware is connected, the software recognizes the device ID and displays the corresponding GUI for the evaluation board. Disconnecting the USB will close the GUI. This tool enables the user to evaluate the sensor features and perform temperature data logging.

Figure 2-4 shows the data acquisition interface with a plot of the thermocouple Hot-Junction and Cold-Junction temperature data. The Y1 axis is the Hot-Junction temperature and the Y2 axis is the Cold-Junction temperature. This data can also be exported by right-clicking the plot and following the export options.

**FIGURE 2-4:** Data Acquisition Interface.
Use the Thermal Management Software Graphical User Interface (GUI) for temperature data logging or to evaluate the sensor board features. If the hardware is properly connected, the software will recognize the hardware, otherwise, the software will show the ‘Hardware Not Detected’ message box, as indicated in Figure 2-5.

![Hardware Not Detected Message Box]

**FIGURE 2-5:** Hardware Not Detected Message Box.
2.5 CONFIGURING THE MCP9600

Figure 2-6 shows the user interface for various sensor options. Once these options are selected, the software programs the device and refreshes the GUI from the device. Therefore the GUI displays the updated device settings.

FIGURE 2-6: Sensor Configuration Options.
2.6 DATA ACQUISITION

The black “Play”, “Stop”, and “Reset” icons (Figure 2-7) can be used to perform continuous data acquisitions. The red “Record” icon enables the user to data log to an external file. The logging interval can be adjusted using the Interval scroll bar from 100 ms to 30s, as shown in Figure 2-4.

The data acquisition display chart (Figure 2-4) can be customized. The customizing options (Figure 2-8) can be selected by either double-clicking or right-clicking the chart (Figure 2-4). The displayed data can also be exported.

FIGURE 2-7: Real-Time Acquisition.

FIGURE 2-8: Chart Setup Options.
Appendix A. Schematic and Layouts

A.1 INTRODUCTION

This appendix contains the following schematics and layouts for the MCP9600 Thermocouple IC Evaluation Board:

• Board Schematic
• Board – Top Silk
• Board – Top Copper and Silk
• Board – Top Copper
• Board – Bottom Copper
• Board – Bottom Copper and Silk
• Board – Bottom Silk
A.2 BOARD SCHEMATIC

---

**Board Components**

- **MCP9600 Thermocouple IC**
- **USB MINI-B Female**
- **Thermocouple**
- **Ferrite Bead**
- **Resistors (R1 - R10)**
- **Capacitors (C1 - C7)**
- **Inductor (L1)**
- **USB-A Male to Mini USB-B Male**

---

**BoardLegend**

- **VCC**
- **GND**
- **SCL**
- **SDA**
- **VIN+ / VIN-**
- **Alert 1 - Alert 4**
- **PIC18F2520-I/SO**
- **U3**
- **C1 / C2 / C3 / C7 / C8 / C9 / C10**

---

**Notes**

- The schematic includes all necessary connections for the MCP9600 Thermocouple IC Evaluation Board.
- Key components are labeled with their respective symbols and values.
- The board also includes a Mini USB-B Male to USB-A Male conversion cable for power and communication.
A.5 BOARD – TOP COPPER

A.6 BOARD – BOTTOM COPPER
A.7 BOARD – BOTTOM COPPER AND SILK

A.8 BOARD – BOTTOM SILK
## Appendix B. Bill of Materials (BOM)

### TABLE B-1: BILL OF MATERIALS (BOM)

<table>
<thead>
<tr>
<th>Qty</th>
<th>Reference</th>
<th>Description</th>
<th>Manufacturer</th>
<th>Part Number</th>
</tr>
</thead>
<tbody>
<tr>
<td>9</td>
<td>Alert 1, Alert 2, Alert 3, Alert 4, GND, GND, SCL, SDA, V&lt;sub&gt;DD&lt;/sub&gt;</td>
<td>Connector TP tab silver mini 3.8x2.03 SMD</td>
<td>Keystone Electronics Corp.</td>
<td>5019</td>
</tr>
<tr>
<td>2</td>
<td>C1, C7</td>
<td>Ceramic capacitor, 1 µF, 50V, 10%, X7R SMD, 0805</td>
<td>Cal-Chip Electronics Inc.</td>
<td>GMC21X7R104K50NTLF</td>
</tr>
<tr>
<td>1</td>
<td>C2</td>
<td>Ceramic Capacitor, 0.1 µF, 25V, 20%, Y5V SMD, 0603</td>
<td>Cal-Chip Electronics Inc.</td>
<td>GMC10Y5V104Z25NTLF</td>
</tr>
<tr>
<td>1</td>
<td>C3</td>
<td>Ceramic capacitor, 0.47 µF, 16V, 10%, X7R SMD, 0805</td>
<td>Panasonic® - ECG</td>
<td>ECJ-2YB1C474K</td>
</tr>
<tr>
<td>2</td>
<td>C4, C5</td>
<td>Ceramic capacitor, 10 µF, 6.3V, 20%, X5R SMD, 0805</td>
<td>Taiyo Yuden Co., Ltd.</td>
<td>JMK212BJ106MG-T</td>
</tr>
<tr>
<td>1</td>
<td>C6</td>
<td>Ceramic capacitor, 1 µF, 16V, 20%, Y5V SMD, 0805</td>
<td>AVX Corporation</td>
<td>0805YG105ZAT2A</td>
</tr>
<tr>
<td>2</td>
<td>FB1, FB2</td>
<td>Ferrite chip beads, 800 mA, 0.15R SMD, 0805</td>
<td>Laird Technologies®</td>
<td>LI0805H151R-10</td>
</tr>
<tr>
<td>0</td>
<td>J1</td>
<td>Connector header, 2.54 male 1x6, tin, 5.84 mm, Through Hole, vertical — DO NOT POPULATE</td>
<td>Sullins Connector Solutions</td>
<td>PEC06SAAN</td>
</tr>
<tr>
<td>1</td>
<td>J3</td>
<td>Connector, Mini USB, B-Type, female, SMD R/A</td>
<td>Hirose Electric Co., Ltd.</td>
<td>UX60-MB-5ST</td>
</tr>
<tr>
<td>1</td>
<td>L1</td>
<td>Inductor, 10 µH, 100 mA, 20%, SMD, 0805</td>
<td>Murata Electronics®</td>
<td>LQM21FN100M70L</td>
</tr>
<tr>
<td>4</td>
<td>PAD1, PAD2, PAD3, PAD4</td>
<td>Mechanical HW rubber pad, square, L12.1xW12.1xH3.1, black</td>
<td>Hammond Manufacturing Ltd.</td>
<td>1421T8BK</td>
</tr>
<tr>
<td>0</td>
<td>PCB</td>
<td>MCP9600 Thermocouple IC Evaluation Board – Printed Circuit Board</td>
<td>—</td>
<td>04-10413-R2</td>
</tr>
<tr>
<td>2</td>
<td>R1, R2</td>
<td>Resistor, TKF 4.99K ohm, 1%, 1/8W, SMD, 0805</td>
<td>ROHM Semiconductor</td>
<td>MCR10EZHF4991</td>
</tr>
<tr>
<td>2</td>
<td>R4, R5</td>
<td>Resistor, TKF 10R, 1%, 1/8W, SMD 0805</td>
<td>ROHM Semiconductor</td>
<td>MCR10EZHF10R0</td>
</tr>
<tr>
<td>0</td>
<td>R6, R7</td>
<td>Resistor, TKF 100K, 1%, 1/8W, SMD 0805 – DO NOT POPULATE</td>
<td>NIC Components Corp.</td>
<td>NRC10F1003TRF</td>
</tr>
<tr>
<td>1</td>
<td>R8</td>
<td>Resistor TF, 100K, 0.1%, 1/8W, SMD 0805</td>
<td>Panasonic® - ECG</td>
<td>ERA-6AEB104V</td>
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<tr>
<td>0</td>
<td>R9, R10</td>
<td>Resistor TKF, 47.5K, 1%, 1/8W, SMD 0805 – DO NOT POPULATE</td>
<td>Panasonic® - ECG</td>
<td>ERJ-6ENF4752V</td>
</tr>
</tbody>
</table>

**Note:** The components listed in this Bill of Materials are representative of the PCB assembly. The released BOM used in manufacturing uses all RoHS-compliant components.
<table>
<thead>
<tr>
<th>Qty</th>
<th>Reference</th>
<th>Description</th>
<th>Manufacturer</th>
<th>Part Number</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>TC1</td>
<td>Mechanical HW adapter thermocouple TH R/A</td>
<td>Omega® Engineering Inc.</td>
<td>PCC-SMP-K-100</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td>(100 pcs. per package)</td>
</tr>
<tr>
<td>1</td>
<td>U2</td>
<td>Sensor temp. ratiometric, 20MQFN</td>
<td>Microchip Technology Inc.</td>
<td>MCP9600-I/MX</td>
</tr>
<tr>
<td>1</td>
<td>U3</td>
<td>Microchip MCU 8-bit, 40 MHz, 32K, 1536B PIC18F2520-I/SO SOIC-28</td>
<td>Microchip Technology Inc.</td>
<td>PIC18F2550T-I/SO</td>
</tr>
<tr>
<td>1</td>
<td>X1</td>
<td>Resonator, 12 MHz, 33 pF, SMD, CSTCE-G</td>
<td>Murata Electronics®</td>
<td>CSTCE12M0G55Z-R0</td>
</tr>
</tbody>
</table>

**Note:** The components listed in this Bill of Materials are representative of the PCB assembly. The released BOM used in manufacturing uses all RoHS-compliant components.

### BILL OF MATERIALS – MECHANICAL PARTS

<table>
<thead>
<tr>
<th>Qty</th>
<th>Reference</th>
<th>Description</th>
<th>Manufacturer</th>
<th>Part Number</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>CBL1</td>
<td>Mech. HW cable USB, A-Type, male to Mini USB, B-Type, 3 ft, black</td>
<td>Qualtek Electronics Corporation</td>
<td>3021003-03</td>
</tr>
<tr>
<td>1</td>
<td>Plugs in TC1</td>
<td>Ready-made insulated thermocouples with Kapton®, PFA, Glass braid insulation and Molded connectors</td>
<td>Omega® Engineering Inc.</td>
<td>5SRTC-TT-K-24-36</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td>(100 pcs. per package)</td>
</tr>
</tbody>
</table>

**Note:** The components listed in this Bill of Materials are representative of the PCB assembly. The released BOM used in manufacturing uses all RoHS-compliant components.